AR759x Specifications

Cellular

`2G` `3G` `4G`

LTE Advanced (Cat-6) with 3G and 2G Fallback

- AR7592 (NAM)
- AR7594 (EMEA)
- AR7596 (China)
- AR7598 (ROW)

Hardware Specs

Dimensions: Auto Grade 32 x 37 x 3.6 mm
Chipset: Qualcomm MDM9x40

Main Interfaces

- Link: USB, UART , PCIe
- Digital: SPI, I2C, GPIO's, Int, SDIO
- Audio: Digital

Temperature Ranges

- -30C to +70C (operating class A)
- -40C to +85C (operating class B)

Key Features

- Automotive-grade manufacturing (TS-16949 certified)
- Automotive quality processes (PPAP, 8D, PCN, FA, …)
- Reliable in extreme operating environments
- GNSS (GPS, Glonass, Galileo, BeiDou)
- Multicore Architecture: ARM Cortex-A7 (1.2GHz) application core dedicated to customer
- Legato®: Open application framework based on Linux
- Advanced voice quality according ITU P.1140

Certification and Approvals

- Planned: FCC, IC, PTCRB, AT&T, T-MO, Verizon, Rogers, RED, Telcel, CE/RED, GCF, Vodafone, CCC, JRF/JPA, Docomo NTT, KT, Telstra, HKT, TW Mobile, Malaysia Digi, SG, SA, ME

ROLLING WIRELESS